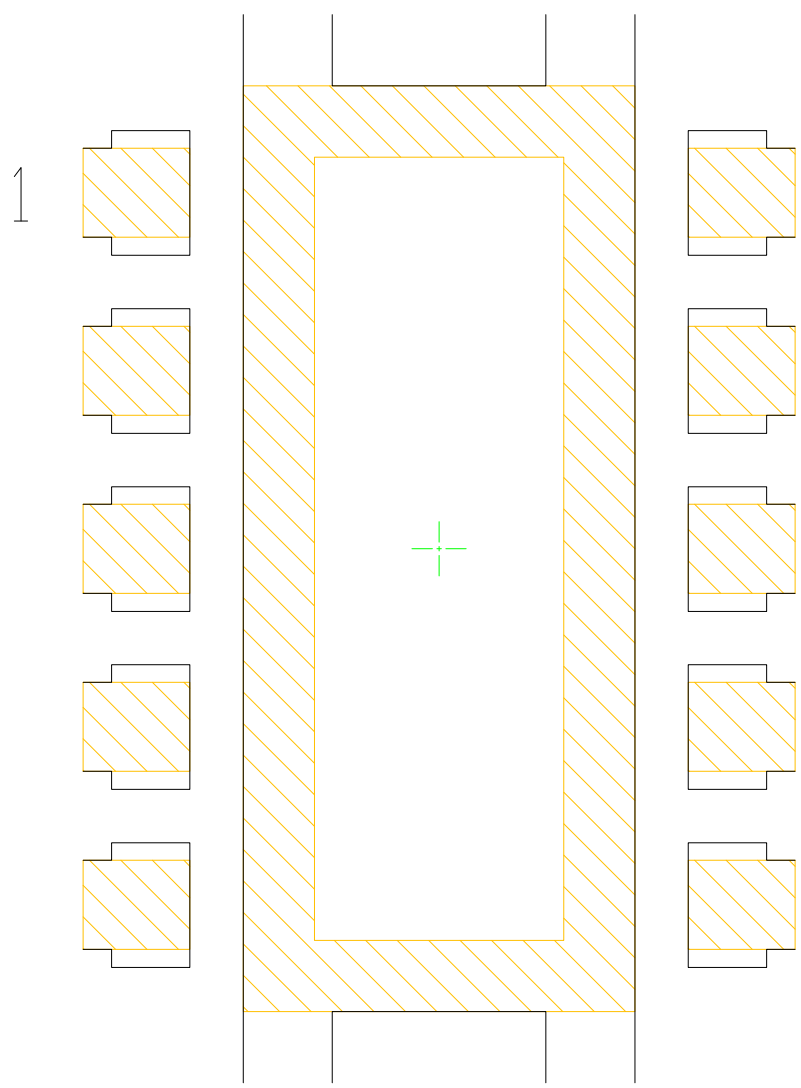


REVISIONS		
REV	DESCRIPTION	DATE
B	ADDED EXPOSED PAD SIZE AND LEADFRAME P/N	4-1-2016



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	<b>PROMEX INDUSTRIES INC.</b> www.promex-ind.com
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.10 x 2.60 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 0.84 x 2.40 mm	TITLE DFN 10L 3x2 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00102
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	REV B
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE
		FILE NAME 10L-DFN-3X2-50P-BD.DWG
		SHEET 1 OF 1